

AMENDMENTS TO THE SPECIFICATION

The following is a complete, marked up listing of the amended paragraphs of the Specification with underlined text indicating insertions, and strikethrough and/or double-bracketed text indicating deletions.

Please amend the paragraph found at page 2, lines 20-28, as follows:

After unloading the semiconductor packages from the molding die 210 by separating the upper molding die 211 and the lower molding die 212 from each other, the cleaning head 231 advances to between the upper molding die 211 and the lower molding die 212. Then, the brush 234 vibrates and [[searates]] separates the resin residues from the molding die 210. The separated resin residues are removed through the vacuum hole 241. This cleaning step is carried out after each molding step.

THE REMAINDER THIS PAGE HAS BEEN LEFT BLANK INTENTIONALLY